



Industrial Computing Platform Partner

ETX-855

Thermal Image Analysis Report

Report No: 05E080023

Release Date: 08/11/2005

2005-08-11

Issue Stamp

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I . Model Name: ETX-855

II . Description: Intel 855 GM/ICH4/Socket 478ETX Board

III . Date: 08/11/2005

IV . Measure Site: AAEON QE Dept.

V . Issued by: Andrew Ku

VI.Equipment:

1. TVS-100 series by NIPPON AVIONICS CO., LTD.

VII. Simulation Environment:

- **Temperature:**

Component Side – 1: 26.4degrees C

- **System Configuration :**

BIOS ver :A0.2

CPU: Intel Dothan Pentium M 2.0GHz

Memory: NANYA / NT5DS64M8AF-6K / SODDR333 / 1GB

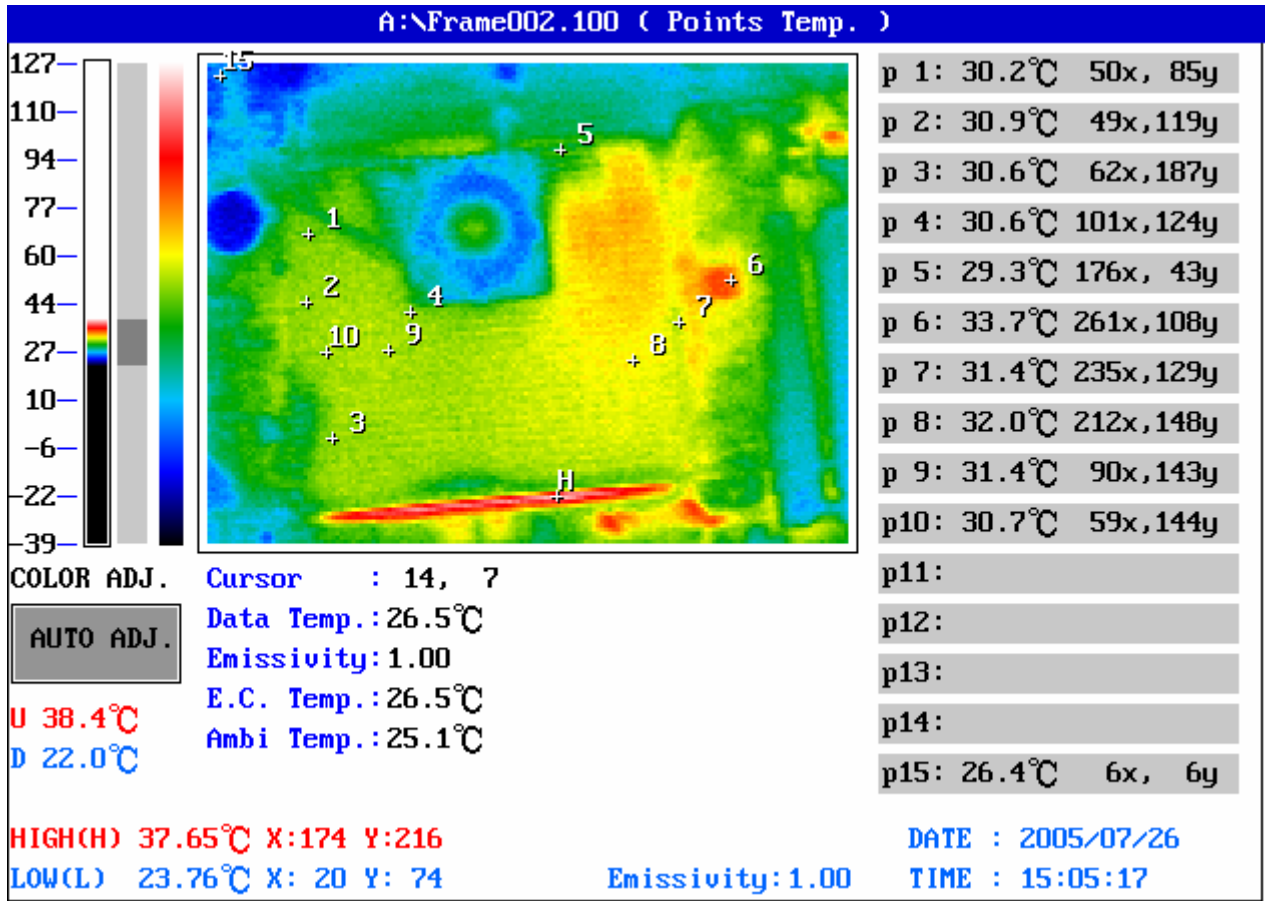
HDD: MAXTOR 80GB

- **Application Software: Windows 2000 run HCT9.5**

- **Take Picture Time: Power on 2 hours after**

Temperature Profile Test:

Component Side – 1:



Point	Position	Describe	Tc	Tm (25°C)	Tm (60°C)	Note
1	U9	IC.SMD.SSOP48 Chipset.INTEL.DA82562ET	0°C~135°C	30.2°C	65.2°C	
2	U19	IC.SMD.IT8712F 128P Super I/O.ITE.IT8712F/GX	0°C~70°C	30.9°C	65.9°C	
3	U4	IC.SMD.Chipset ICH4.INTEL.FW82801DB SL6DM	0°C~100°C	30.6°C	65.6°C	
4	U3	IC.SMD.Chipset MONTARA.INTEL.RG82855GME	0°C~100°C	30.6°C	65.6°C	
5	L5	(TF)COIL.1.0uH.SMD.12.9*12.9*5mm.DCR=2.1m ohm.Idc=29Amp.VISHAY.HLP5050EZER1R0M01	-55°C~125°C	29.3°C	64.3°C	
6	Q25	REG.SMD.SOT-223.1A Dropout Regulator.AMS.AMS1117-3.3	--35°C~120°C	33.7°C	68.7°C	
7	U42	IC.SMD TFBGA.160P.PCI to ISA Bridge Chip.ITE.IT8888G	0°C~70°C	31.4°C	66.4°C	
8	U2	(TF)IC.SMD.SSOP 56P.CLOCK GENERATOR.ICS.ICS952601FLFT	0°C~115°C	32.0°C	67.0°C	
9	L8	INDUCTOR.3.3uH.20%.SMDDCR=12mohm Isat=27A.VISHAY.IHLP2525CZRZ3R3M01	-25°C~95°C	31.4°C	66.4°C	
10	C14	MCC.10uF.10V.20%.X5R 0805.SMD	-55°C~150°C	30.7°C	81.6°C	
11						
12						
13						
14						
15		Ambient Temperature		26.4°C		

1. Operation Temperature (°C):

$$T_c(\text{Case temp.}) = T_a(\text{Ambient Temp.}) \pm 30^\circ\text{C} = T_j(\text{Junction Temp.}) \pm 25^\circ\text{C}$$

Note: The description in red states which temperature is over the specification of the device.